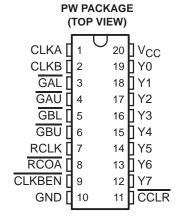
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- Controlled Baseline
 - One Assembly Site
 - One Test Site
 - One Fabrication Site
- Extended Temperature Performance of -55°C to 125°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- Can Be Used as Two 16 Bit Counters or a Single 32 Bit Counter
- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 25 ns at 5 V (RCLK to Y)
- Typical V_{OLP} (Output Ground Bounce)
 <0.7 V at V_{CC} = 5 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot) >4.4 V at V_{CC} = 5 V, T_A = 25°C
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17

- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.



description/ordering information

The SN74LV8154 is a dual 16 bit binary counter with 3-state output registers, designed for 2-V to 5.5-V V_{CC} operation.

This 16 bit counter (A or B) feeds a 16 bit storage register and each storage register is further divided into an upper byte and lower byte. The GAL, GAU, GBL, and GBU inputs are used to select the byte that needs to be output at Y0–Y7. CLKA is the clock for A counter and CLKB is the clock for B counter. RCLK is the clock for the A and B storage registers. All three clock signals are positive-edge triggered.

A 32 bit counter can be realized by connecting CLKA and CLKB together and by connecting RCOA to CLKBEN.

To ensure the high-impedance state during power up or power down, \overline{GAL} , \overline{GAU} , \overline{GBL} , and \overline{GBU} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION[†]

TA	PACK	AGE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-55°C to 125°C	TSSOP - PW	Tape and reel	SN74LV8154MPWREP	LV8154ME

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/packaging.



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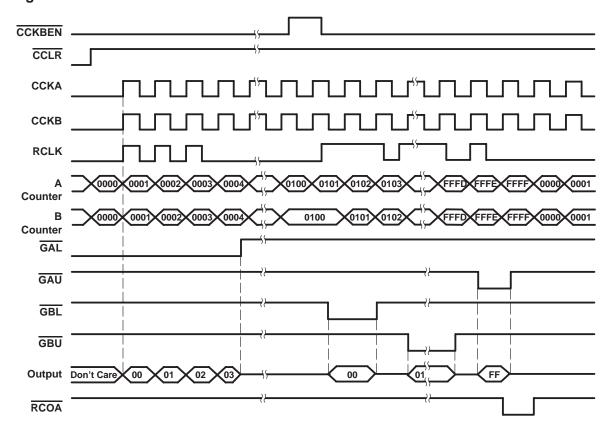


FUNCTION TABLE (each buffer)

	INP	UTS		OUTPUT
GAL	GAU	GBL	GBU	Yn
L	Н	Н	Н	Lower byte in A register
Н	L	Н	Н	Upper byte in A register
Н	Н	L	Н	Lower byte in B register
Н	Н	Н	L	Upper byte in B register
Н	Н	Н	Н	Z

Combinations of GAL, GAU, GBL, and GBU, other than those shown above, are prohibited. If more than one input is L at the same time, the output data (Y0–Y7) may be invalid.

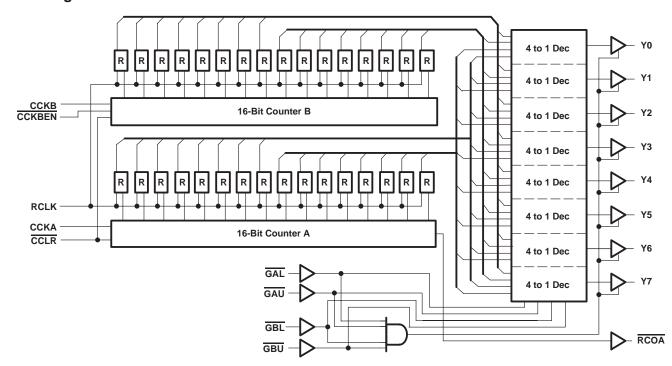
timing diagram





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block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	–0.5 V to 7 V
Output voltage range, VO (see Note 1 and Note 2)	\dots -0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0 V)	–20 mA
Output clamp current, I _{OK} (V _O < 0 V)	–50 mA
Continuous output current, I_O ($V_O = 0 V$ to V_{CC})	±35 mA
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ _{JA} (see Note 3):	
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



SN74LV8154-EP DUAL 16 BIT BINARY COUNTER WITH 3-STATE OUTPUT REGISTERS

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recommended operating conditions (see Note 4)

			VCC	MIN	MAX	UNIT	
VCC	Supply voltage			2	5.5	V	
			2 V	1.5			
V_{IH}	High-level input voltage	3 V to 3.6 V	V _{CC} ×0.7		V		
			4.5 V to 5.5 V	V _{CC} ×0.7			
			2 V		0.5		
٧ _{IL}	Low-level input voltage		3 V to 3.6 V		V _{CC} ×0.3	V	
			4.5 V to 5.5 V		V _{CC} ×0.3		
٧ _I	Input voltage			0	5.5	V	
.,	0	High or low state		0	Vcc	.,	
VO	Output voltage	3-state		0	5.5	V	
			2 V		-50	μΑ	
		Yn outputs	3 V to 3.6 V		-6		
			4.5 V to 5.5 V		-12	mA	
ЮН	High-level output current		2 V		-50	μΑ	
		RCOA	3 V to 3.6 V		-6		
			4.5 V to 5.5 V		-12	mA	
			2 V		50	μΑ	
		Yn outputs	3 V to 3.6 V		6		
	Level bear level and and assessed		4.5 V to 5.5 V		12	mA	
lOL	Low-level output current		2 V		50	μΑ	
		RCOA	3 V to 3.6 V		6		
			4.5 V to 5.5 V		12	mA	
		•	3 V to 3.6 V		100	0.1	
Δt/Δν	Input transition rise or fall rate		4.5 V to 5.5 V		20	ns/V	
TA	Operating free-air temperature			-55	125	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See the TI application report, *Implications* of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	VCC	MIN	TYP	MAX	UNIT	
		$I_{OH} = -50 \mu\text{A}$	2 V	1.9				
	Yn	$I_{OH} = -6 \text{ mA}$	3 V	2.48				
.,		$I_{OH} = -12 \text{ mA}$	4.5 V	3.8			T	
VOH		$I_{OH} = -50 \mu\text{A}$	2 V	1.9			V	
	RCOA	$I_{OH} = -6 \text{ mA}$	3 V	2.48				
		$I_{OH} = -12 \text{ mA}$	4.5 V	3.8				
		$I_{OL} = 50 \mu A$	2 V			0.1		
	Yn	$I_{OL} = 6 \text{ mA}$	3 V	3 V		0.44		
		$I_{OL} = 12 \text{ mA}$	4.5 V			0.55	.,	
VOL		$I_{OL} = 50 \mu A$	2 V			0.1	V	
	RCOA	$I_{OL} = 6 \text{ mA}$	3 V			0.44		
		$I_{OL} = 12 \text{ mA}$	4.5 V			0.55		
lį		$V_I = 5.5 \text{ V or GND}$	0 V to 5.5 V			±1	μΑ	
loz		$V_O = V_{CC}$ or GND	5.5 V			±5	μΑ	
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			20	μΑ	
off		V_I or $V_O = 0 V$ to 5.5 V	0 V			5	μΑ	
C _i	_	$V_I = V_{CC}$ or GND	5 V		3		pF	
Co		$V_O = V_{CC}$ or GND	5 V		5	·	pF	

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

			MIN	MAX	UNIT			
	Dulas duration	CLKA, CLKB, and RCLK high or low						
t _W	Pulse duration	CCLR low	22		ns			
		CLKBEN low before CLKB↑	13					
		CCLR high (inactive) before CLKA↑ or CLKB↑						
t _{su}	3u	p time CLKA↑ or CLKB↑ before RCLK↑						
		RCLK↑ before GAL, GAU, GBL, or GBU low	13					
		GAL, GAU, GBL, or GBU high (inactive) before RCLK↑	13					
4.	Hald Care	CLKBEN low after CLKB↑	0					
чh	t _h Hold time	CLKA or CLKB after RCLK	0		ns			
t _z †	Z-period	GAL, GAU, GBL, and GBU all high before one of them switches low	200		ns			

[†] t_z condition: $C_L = 50$ pF, $R_L = 1$ k Ω



SN74LV8154-EP DUAL 16 BIT BINARY COUNTER WITH 3-STATE OUTPUT REGISTERS

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timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			MIN	MAX	UNIT
	Delega demotion	CLKA, CLKB, and RCLK high or low	10		
t _W	Pulse duration	CCLR low	20		ns
		CLKBEN low before CLKB↑	10		
		CCLR high (inactive) before CLKA↑ or CLKB↑			
t _{su}	Setup time	CLKA↑ or CLKB↑ before RCLK↑	10		ns
		RCLK↑ before GAL, GAU, GBL, or GBU low	10		
		GAL, GAU, GBL, or GBU high (inactive) before RCLK↑	10		
		CLKBEN low after CLKB↑	0		
^t h	t _h Hold time	CLKA or CLKB after RCLK	0		ns
tz†	Z period	GAL, GAU, GBL, and GBU all high before one of them switches low	200		ns

 t_z condition: $C_L = 50$ pF, $R_L = 1$ k Ω

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T _A = 25°C	MINI	MAY	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	TYP	MIN	MAX	UNII
fMAX			$C_L = 50 pF$		25		MHz
+ .	RCLK	Υ		25	1	42	
^t pd	CLKA	RCOA		28	1	46	ns
^t PLH	CCLR	RCOA	C _L = 50 pF	20	1	35	ns
t _{en}	GAL, GAU, GBL, GBU	Υ		30	1	50	ns
^t dis	GAL, GAU, GBL, GBU	Υ		14	1	24	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO	LOAD	T _A = 25°C	MIN	MAX	UNIT
	(INPUT)	(OUTPUT)	CAPACITANCE	TYP			
fMAX			$C_{L} = 50 \text{ pF}$		25		MHz
	RCLK	Υ		16	1	27	
^t pd	CLKA	RCOA		17	1	28	ns
^t PLH	CCLR	RCOA	C _L = 50 pF	13	1	21	ns
t _{en}	GAL, GAU, GBL, GBU	Υ		18	1	30	ns
^t dis	GAL, GAU, GBL, GBU	Υ		9	1	16	ns

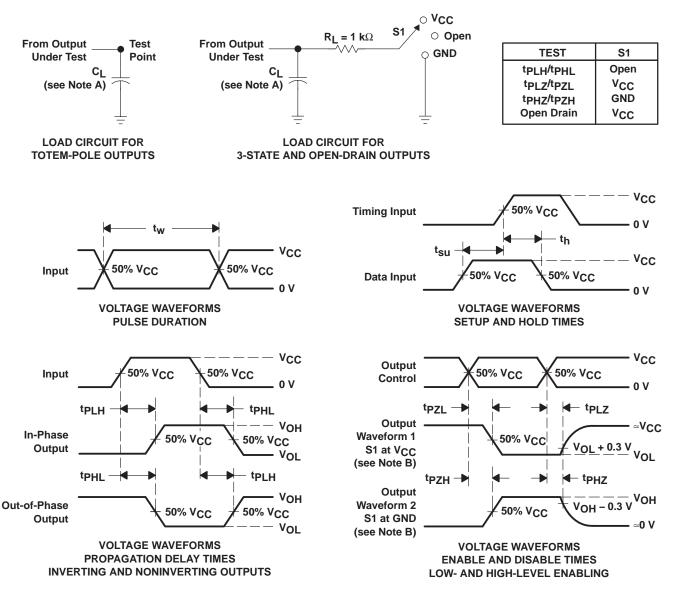
noise characteristics, V_{CC} = 5 V, C_L = 50 pF

	DADAMETED	T _A = 25°C	UNIT				
	PARAMETER						
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}	0.7	V				
V _{OL(V)}	Quiet output, minimum dynamic VOL	-0.75	V				
V _{OH(V)}	Quiet output, minimum dynamic VOH	4.4	V				

operating characteristics, V_{CC} = 5 V, T_A = 25 $^{\circ}C$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance	C _L = No load, CCLK = 10 MHz, RCLK = 1 MHz	56	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuits and Voltage Waveforms





PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

www.ti.com

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV8154MPWREP	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LV8154ME	Samples
V62/06662-01XE	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LV8154ME	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

10-Dec-2020

OTHER QUALIFIED VERSIONS OF SN74LV8154-EP:

• Catalog: SN74LV8154

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

PACKAGE MATERIALS INFORMATION

www.ti.com 17-Dec-2020

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV8154MPWREP	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74LV8154MPWREP	TSSOP	PW	20	2000	853.0	449.0	35.0	

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

- All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
 C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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